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PATENT  
Attorney Docket No. SEL 189

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Toru TAKAYAMA, et al.

Serial No.: 09/598,736

Filed: June 21, 2000

Examiner: Hung K. Vu

Art Unit: 2811

For: WIRING MATERIAL, SEMICONDUCTOR  
DEVICE PROVIDED WITH A WIRING USING  
THE WIRING MATERIAL AND METHOD OF  
MANUFACTURING THEREOF

Commissioner for Patents  
Washington, D.C. 20231

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AMENDMENT A

Dear Sir:

In response to the Office Action mailed December 20, 2001, please amend the above-identified patent application as follows.

IN THE CLAIMS:

Sub B<sup>1</sup>  
Please amend claims 1, 3-33, 38-45, and 50-52 to read as follows:

1 (Amended). A semiconductor device comprising:

a wirings formed over a substrate, the wirings comprising tungsten or a tungsten compound  
as a main constituent,